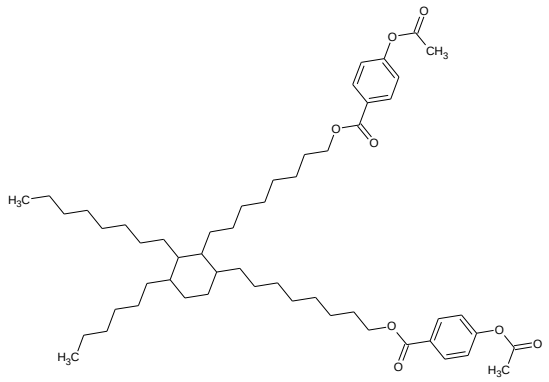
TECH DATA SHEET

EC-861



DESCRIPTION

EC-861 is a phenyl acetate epoxy curative. When cured with an epoxy, the resulting thermoset displays a high level of toughness and flexibility. The monomer is hydrophobic by nature and results in more hydrophobic thermosets. The low viscosity (which can result in lower viscosity in final products) makes it an ideal monomer to formulate in epoxy resin systems. The phenyl acetate end group, unlike phenolics, does not interfere with free-radical cure in hybrid adhesive systems.

HIGHLIGHTS

- Low modulus
- Toughener
- Hydrolytically resistant thermosets
- Hydrophobic
- Thermal stability
- Does not impede free-radical cure

TYPICAL PHYSICAL AND CHEMICAL PROPERTIES

PROPERTY	METHOD	RESULT
Appearance at Room Temperature	Visual	Yellow liquid
Viscosity @ 25°C (typical)	Haake Rheometer	3,000 cP
Functionality		2
Molecular Weight		861 daltons
Onset of Decomposition	TGA	> 350°C
Recommended Storage Temp		Room Temperature

Data is for reference only and may vary depending on testing method used. The structure shown above is an idealized representation of a statistical distribution.

RECOMMENDED FORMULATION USE:

EC-861 is recommended for use as an epoxy curative for systems requiring a high level of toughness, hydrophobicity, and low modulus. EC-861 curative should be used in conjunction with multifunctional epoxies or in the presence of about a 20% excess of difunctional epoxies if a thermoset is desired.

Formulations containing approximately one-to-one equivalent levels with difunctional epoxies can result in tough thermoplastics. Standard epoxy catalysts such as amines, imidizoles, and Lewis acids can also work to cure EC-861 with epoxy resins.

CONTACT:

REQUEST A SAMPLE OR PLACE AN ORDER

Customer Support
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REF: DMI Part Number: R1165